

Mil-grade next-generation fiber optic on-board transceivers

Connecting the world at the speed of light \equiv



AOP Focus Areas

MILITARY & AEROSPACE

- Ground Vehicle
- Maritime
- Radar
- Avionics
- Missiles
- Sattelites
- IFE
- Electronic Warfare

INDUSTRIAL

- Telescopes
- Al Supercomputers
- Particle Accelerators
- Hardware Emulation
- AOI Systems
- Server Networking
- Industrial Instrumentation

COMMERCIAL

- Al Desktop PC
- Perconal Computer
- Datacom Networking
- Datacentre
- Storage
- 5G

and more.

and more.

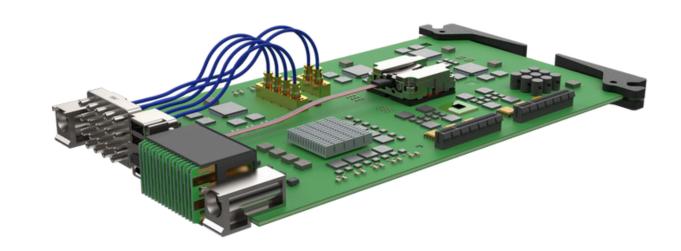
and more.

Problem

In current SFP+ designs, how to minimize trace losses to save link budget, increase bandwidth, reduce board space and overall weight, while also maintaining low cooling requirements and power consumption, all while ensuring EMI/RFI protection?



Solution

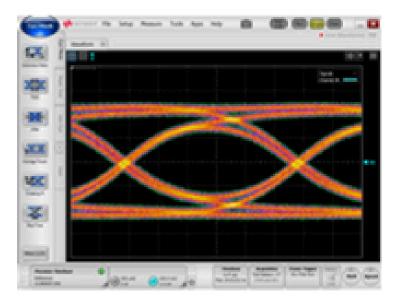


AOP ON-BOARD TRANSCEIVERS SAVES → ~12 dB

Higher data rates and advanced modulation to enhance bandwidth with a compact design integrating multiple functions, saving space and weight. Our transceivers consume less power, reducing cooling needs, and operate with light signals, practically eliminating any susceptibility to electromagnetic interference (EMI) and radio frequency interference (RFI). Overall, we enable more efficient, reliable, and compact designs for modern high-speed data communication systems.

Eye Diagram

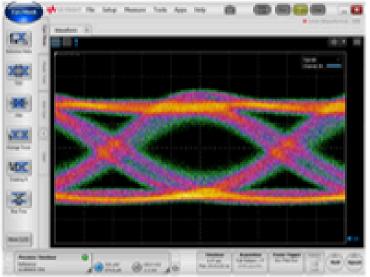
EQUALIZER



TX input eye



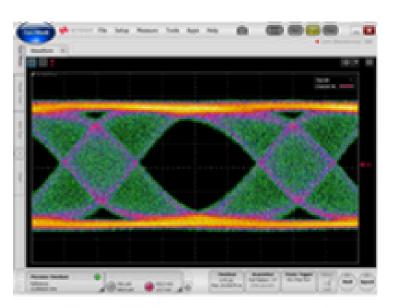
TX output eye MidEQ=0, HiEQ=0



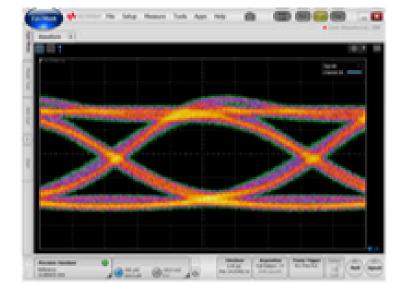
TX output eye MidEQ=15, HiEQ=4

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CDR



Bad TX input signal



TX output eye CDR ON

Eye Diagram

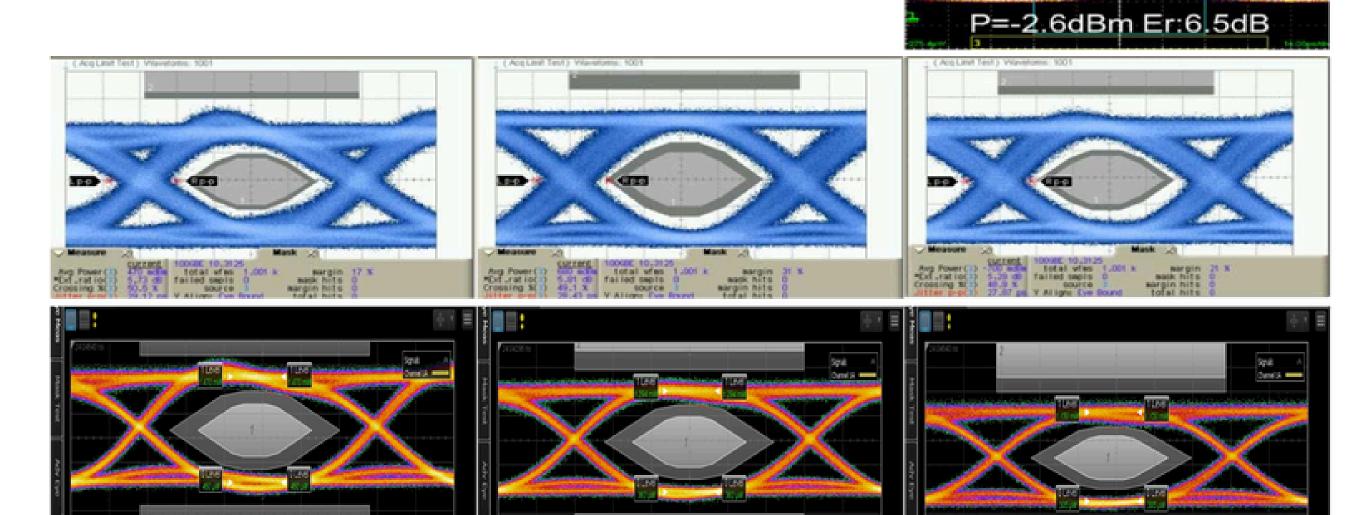
-40°C +25°C +85°C

90°C

COMPETITOR 1

COMPETITOR 2

Amphenol Active Optics
Products





Portfolio Snapshot

MIL-AERO G R A D E

-40°C TO +85°C STD-883 SHOCK & VIBE

SCFF

Small Cubic Form Factor



- •1TX + RX
- Multimode 850nm
- 10 & 25 Gbps / channel
- Half size of SFP+
- LC connection
- Solderable



QEPT

Quad Embedded Pluggable Transceiver



- 4 TX + RX
- Multimode 850nm
- 28 & 56 Gbps / channel
- Hot pluggable
- Fiber removable
- Easy path to PAM4



LEAP® OBT

On-board Transceiver



- 12 TX + RX
- Multimode 850nm
- 16 & 25 Gbps / channel
- World's Fastest & Smallest
- Fiber Removable
- LGA Mountable



PERFORMANCE

1-channel multi-mode (1TX +1RX)

28 Gbps per channel

BER < 10⁻¹²

Operating Temp: -40°C TO 85°C

Power Consumption: <1.1 W

Radiation Resistant: 100 krad*

FEATURES

Integrated CDR

TX Equalizer

RX Amplifier. & De-empahsys

Digital Monitoring

MECHANICAL INFO

Die-casted housing

Standard LC duplex

Solderable Connector

STD-883 Shock & Vibe

DIFFERENTIAL

Chip onboard technology

Radiation resistant

*to be qualified by similarity ** 10 Gbps version available

SCFF 28G

NRZ

Small Cubic Form Factor



Key Features

- Single-channel duplex transceiver
- Any data-rate from 1.25 up to 28 Gbps per channel**
- -40°C to 85°C operating case temperature
- Standard duplex LC-connector
- 12-pin solderable proprietary connector

PERFORMANCE

12-channel multi-mode (12TX +12RX)*

25 Gbps per channel

BER < 10⁻¹²

Operating Temp: 0°C TO 70°C

Power Consumption: 6.0 W

FEATURES

Integrated CDR

TX Equalizer

RX Amplifier. & De-empahsys

Digital Monitoring

Internal PRBS9, PPG & ED

MECHANICAL INFO

Various heat sink versions

Plugabble MT-24 Ferrule

Amphenol LGA/BGA Socket Mounted

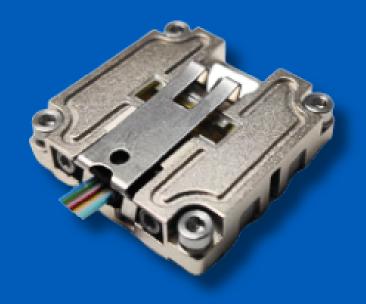
DIFFERENTIAL

World's Fastest & Smallest

Power Consumption

LEAP OBT 300G NRZ

On-board Transceiver



Key Feautures

- 12-channel duplex transceiver
- Any data-rate from 1 up to 25 Gbps per channel (300 Gbps aggregate data rate)
- 0°C to 70°C operating case temperature
- Standard MT-24 ferrule compatible
- LGA mounted

PERFORMANCE

12-channel multi-mode (12TX +12RX)*

16 Gbps per channel

BER < 10⁻¹²

Operating Temp: -40°C TO 85°C

Power Consumption: 3.5 W

FEATURES

TX Equalizer

RX Amplifier. & De-empahsys

Digital Monitoring

Internal PRBS9, PPG & ED

MECHANICAL INFO

Various heat sink versions

Plugabble MT-24 Ferrule

Amphenol LGA/BGA Socket Mounted

STD-883 Shock & Vibe

DIFFERENTIAL

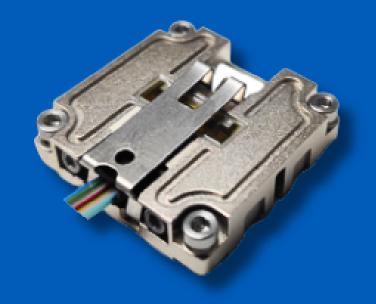
World's Fastest & Smallest

Power Consumption

Mil-graded

LEAP RUGGED 192G NRZ

On-board Transceiver



Key Feautures

- 12-channel duplex transceiver
- Any data-rate from 1 up to 16 Gbps per channel (192 Gbps aggregate data rate)
- -40°C to 85°C operating case temperature
- Standard MT-24 ferrule compatible
- LGA mounted

Amphenol Active Optics

PERFORMANCE

4-channel multi-mode (4TX +4RX)*

28 Gbps per channel

BER < 10⁻¹²

Operating Temp: -40 °C TO 85 °C

Power Consumption: 1.6 W

FEATURES

Integrated CDR

TX Equalizer

RX Amplifier. & De-empahsys

Digital Monitoring

MECHANICAL INFO

Flat top or heat sink versions

Standard MT-Ferrule

Mezzanine Connector

STD-883 Shock & Vibe

DIFFERENTIAL

Hot-Pluggable

Same footprint for PAM4 version

Radiation resistant

QEPT 100G NRZ

Quad Embedded Pluggable Transceiver



Key Features

- 4-channel duplex transceiver*
- Any data-rate from 1.25 up to 28Gbps per channel
- -40°C to 85°C operating case temperature
- Pluggable MT-12F ferrule
- Hot-pluggable mezzanine mounted

^{* 8-}TX and 8-RX versions in development

^{**} next page

PERFORMANCE

4-channel multi-mode (4TX +4RX)*

56 Gbps PAM4 per channel

BER < $2.4 \cdot 10^{-4}$

Operating Temp: 0 °C TO 70 °C

Power Consumption: 3.0 W

FEATURES

Integrated CDR

TX Equalizer

RX Amplifier. & De-empahsys

Digital Monitoring

Internal PRBS13Q, PPG & ED

MECHANICAL INFO

Flat top or heat sink versions

Standard MT-Ferrule

Mezzanine Connector

DIFFERENTIAL

Hot-Pluggable

Same footprint as NRZ version

QEPT 200G PAM4

Quad Embedded Pluggable Transceiver



Key Features

- 4-channel duplex transceiver*
- Any data-rate from 1.25 up to 25Gbps NRZ
- or 56Gbps PAM4 per channel
- 0°C to 70°C operating case temperature
- Pluggable MT-12F ferrule
- Hot-pluggable mezzanine mounted

Amphenol Active Optics

Products	SCFF	DUAL SCFF	QEPT 100 NRZ	QEPT 200 PAM4	QEPT TX/RX	LEAP RUGGED	LEAP OBT 300G
TX/RX	TX+RX	TX+RX	TX+RX	TX+RX	TX or RX	TX+RX	TX+RX
Number of Channels	1+1	2+2	4+4	4+4	8	12 + 12	12 + 12
Aggregated Data Rate (Gbps)	10 or 25	20 or 50	100	200	100	192	300
Size LxWxH (mm)	26x14x10	36x30x12	29x18x9	29x18x9	29x18x9	24x24x8	24x24x8
Multimode	~	~	~	~	✓	✓	✓
Wavelength (nm)	850	850	850	850	850	850	850
Modulation	NRZ	NRZ	NRZ	PAM4	NRZ	NRZ	NRZ
Operating Temperature Minimum, Maximum (°C)	-40, +85	-40, +85	-40, +85	0, +70	-40, +85	-40, +85	0, +70
Vibe MIL-883	~	✓	~	~	✓	✓	*
Shock MIL-883	✓	✓	✓	✓	✓	✓	*
Power Dissipation (W)	10G: 0.45 25G: 0.65	20G: 0.90 50G: 1.30	1.5	3.0	1.5	3.5	5.8
Mounting	Soldering	Daughter card		Mezzanine connector		BGA socket	BGA socket
Heat Dissipation	Die-cast housing	Die-cast housing	Heatsink, coldplate				
Fiber Connection	LC	LC	MT-12 ferrule	MT-12 ferrule	MT-12 ferrule	MT-24 ferrule	MT-24 ferrule
Hot-Pluggable	×	×	~	✓	✓	X	×
Fiber cable can be replaced	~	✓	✓	✓	✓	~	✓
Bit Error Rate (BER)	< 10 ⁻¹²	< 10 ⁻¹²	< 10 ⁻¹²	<2.4*10-4	< 10 ⁻¹²	< 10 ⁻¹²	< 10 ⁻¹²
Two-wire serial interface (i²c)	✓	✓	✓	~	✓	✓	✓
CDR (Clock Data Recovery)	~	✓	~	~	✓	X	✓
Input Equalization, Output Amplitude & Pre-Emphasis	✓	✓	✓	~	✓	✓	✓
Digital Monitoring (Voltage, Temperature, RSSI)	~	~	~	~	✓	✓	✓
Evaluation Kit Available	~	~	~	~	coming soon	✓	✓
Parts Available	~	~	~	coming soon	coming soon	~	~
Packaging (pcs)	10	10	10	10	10	1 or 10	1 or 10

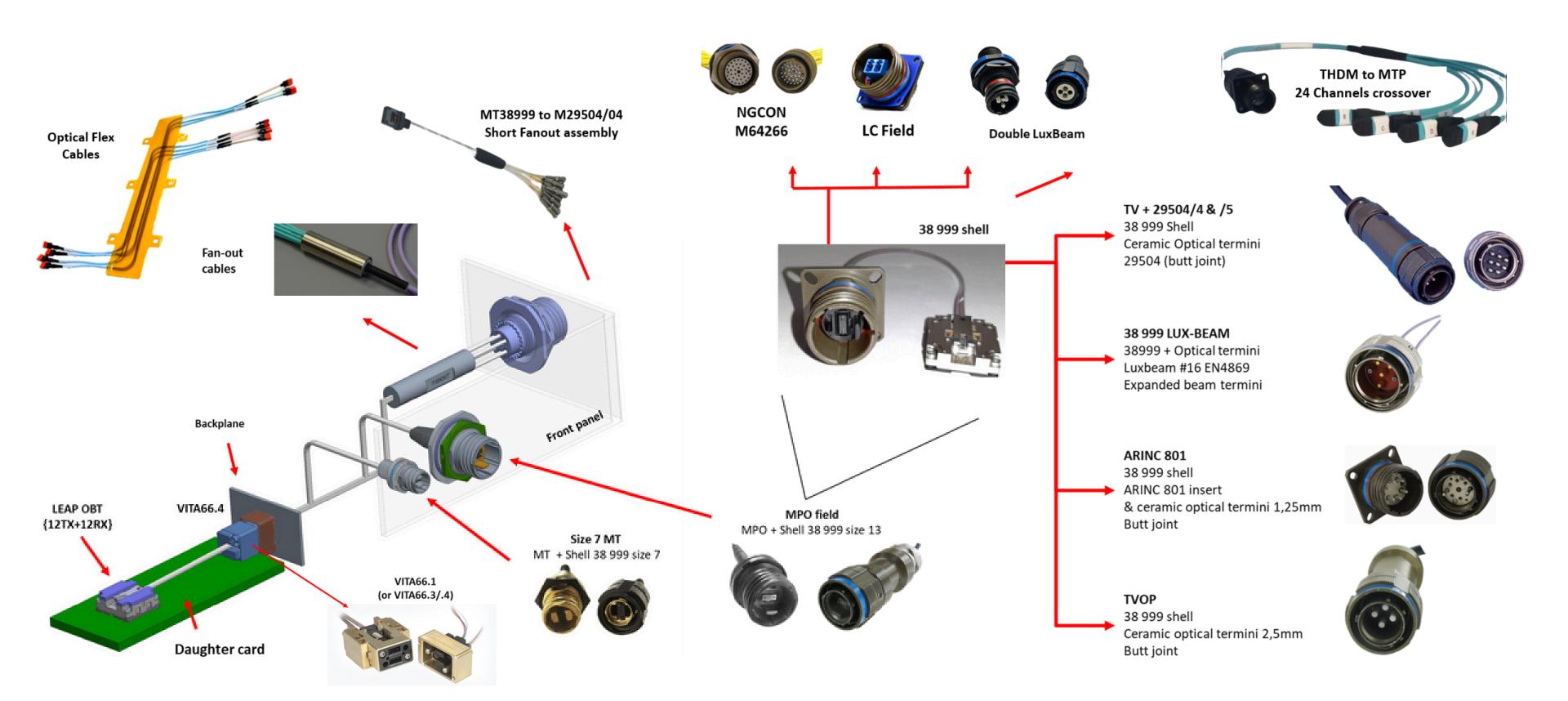
^{*:} qualified per similarity

Product Matrix Comparison



Open.Tech by Amphenol

END TO END SOLUTIONS

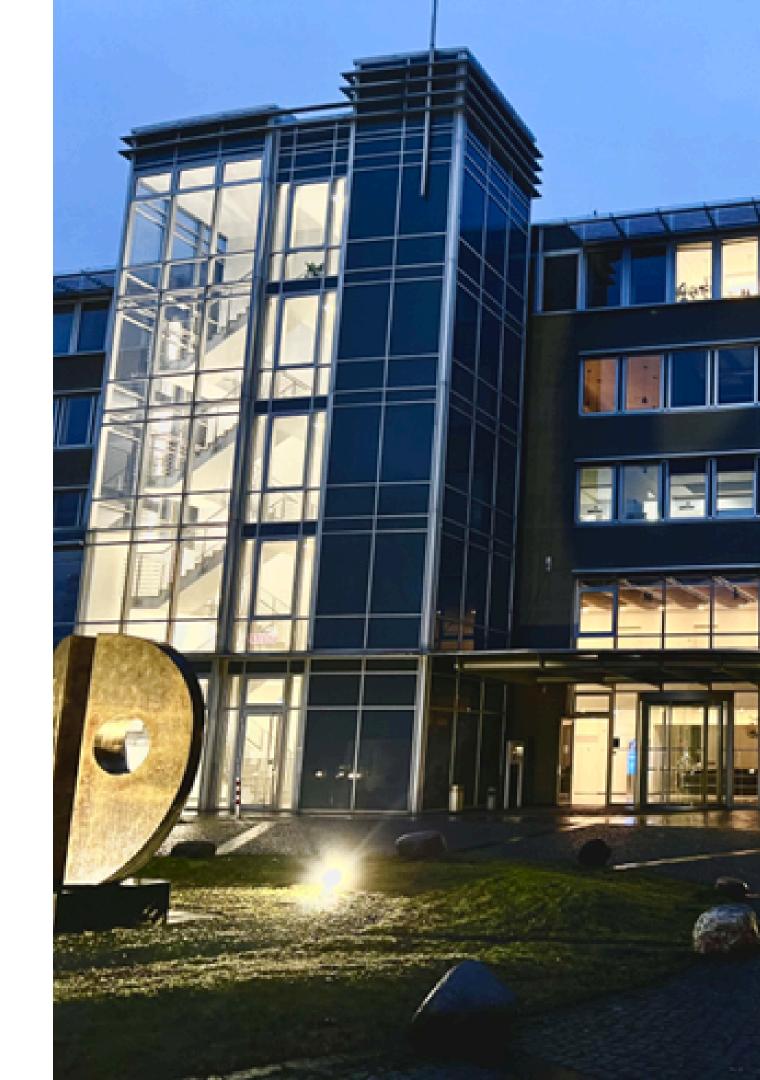






Amphenol AOP

- Founded in 2003 (MergeOptics GmbH)
- Located in Berlin
- ISO 9001 & 14001 certified
- Capabilities
 - Product Development
 - Process Development
 - Machine Development
 - NPI and Manufacturing
- 22 years of proven track record in designing and manufacturing optoelectronic products.
- Core competencies in RF, optical packaging, optical engine integration, assembly process
- Product, process development and manufacturing hosted at the same location.



ROCESS

CTURING

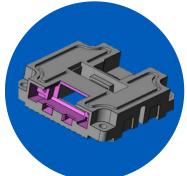
AOP Capabilities

DEVELOPMEN



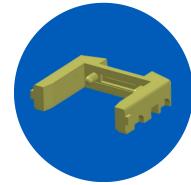
ELECTRONIC DESIGN

Transceiver & Active Optical Cables PCB design and component integration Connector design for optimal SI



MECHANICAL DESIGN

Die-casted and machined parts designs Tolerance analysis Simulations (thermal, mechanical stress)



OPTICAL DESIGN

Lens design for parallel optical beams Mechanical designs of plastic molded parts



FIRMWARE & TEST

Firmware design programming Standard compliant or customized FW E/O performance testing capability Characterization over temperatures and voltages



High volume / high accuracy die-bonding High-capacity gold wire bonding equipment Development of tooling & processes



BURN-IN

VCSEL burn-in process development High-capacity burn-in equipment Pre- and post burn-in VCSEL characterization



ACTIVE OPTICAL ALIGNMENT

Customized alignment station development Automated optimal coupling process Alignment algorithms programming



HIGH-SPEED E/O TEST

Fully automated E/O tester design Measurements from -40°C to 85°C Internal software development





Amphenol AOP - Process Flow



Wire-bonding

High-speed die bonding



Higher burn-in capacity



Expansion: 3x production area in 2021



New product lines



In-house active optical alignment



START

Garment room



Entrance area



Automated DC testing

High accuracy



Automated RF testing







AOP Differentiators

PORTFOLIO

Latest generation designs:

- High performance
- Safer supply chain (risk of EOL minimized)

Extended range of data rates / channels supported:

- Single, 4-channel and 12-channel
- From 1.25Gbps to 16Gbps,
 28Gbps or even 56Gbps*
- Footprint can be re-used over several generations (QEPT platform

PLUGGABILITY

Optical pluggability: optical cables can be removed

- Easier/more flexible routing
- Cost effective replacement in case of fiber damage

New: hot-pluggability (QEPT platform)

- No need to shut down system to insert / remove transceiver
- Plug & play solution

THERMAL DESIGNS

Effective heat dissipation

- Heat dissipated towards the top for use of cooling plate
- No constraints in customer board design (no dissipation inside the board)

Effective mechanical designs:

- Die-casted housings
- Support customized heat-sink designs

Evaluation Kits

EVALUATION BOARDS

Designed to streamline and increase your go-to market time.

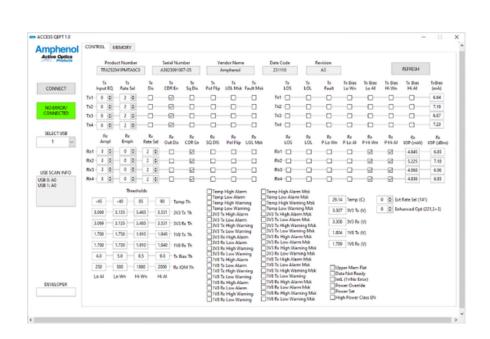
KEY FEAUTURES

- Evaluation board including high-speed electrical I/O
- Functional transceiver
- USB to i²c adapter
- Graphical User Interface software to access customer registers
- Fiber Optics cable assemblies and RF cables available in option

AVAILABLE VERSIONS

- LEAP® OBT 300G
- Ruggedised LEAP OBT
- Ruggedised SCFF
- QEPT 100G NRZ
- QEPT 200G PAM4*







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